

EC360BLUE

Thermal Pad Series

The EC360® BLUE series presents silicone-based thermal pads with the best price-performance ratio regarding thermal conductivity. It features the highest thermal conductivity for our silicone-based thermal pads of 5 W/mK and is suitable for a variety of applications including GPUs (that are cooled by thermal pads), memory chips and other electrical components.

It is the perfect solution for heat-transfer in adverse surface conditions when the use of thermal paste is unsuitable. Being based on silicone, they have good elasticity and compression abilities. This means this type of thermal pad will spring back into its original form even after longer periods of compression and perfectly adapt to any tiny surface irregularity.

Cross-section view



A full silicone pad covered with a PET film on both contact surfaces for increased stability and easy installation. Both are to be removed for installation.

* Custom configurations are available upon request, for worldwide industrial inquiries please contact us at: sales@extremecool360.com

Types and Configurations

Thickness*	Available sizes*
0.5 mm / 0.02 "	50x50 mm, 100x100 mm, 200x200 mm
1.0 mm / 0.04 "	50x50 mm, 100x100 mm, 200x200 mm
1.5 mm / 0.06 "	50x50 mm, 100x100 mm, 200x200 mm
2.0 mm / 0.08 "	50x50 mm, 100x100 mm, 200x200 mm
3.0 mm / 0.12 "	50x50 mm, 100x100 mm, 200x200 mm
4.0 mm / 0.16 "	50x50 mm, 100x100 mm, 200x200 mm
5.0 mm / 0.20 "	50x50 mm, 100x100 mm, 200x200 mm

Technical Properties

Properties	Unit	Value	Test method
Color	-	blue	Visual
Thermal Conductivity	W/mK	5.0	ASTM D5470
Specific Gravity	g / cm ³	2.5	ASTM D 792
Hardness	Shore C	35	ASTM D 2240
Tensile Strength	psi	71	ASTM D 412
Volume Impedance	Ohm-cm	2.9 x10 ¹¹	ASTM D 257
Breakdown Voltage	kV/mm	5.0	ASTM D 149
Usable Temperatures	°C	-40 - 250	EN 344
Flame Rating	-	VO	UL 94

Installation Recommendation

- Clean surfaces from dirt and other possible residue. If applicable, isopropyl 90% alcohol is recommended to ensure a clean surface.
- Remove one of the protective layers and place the exposed side of the thermal pad facing the surface of the chip. Once positioned gently press on it to make it stick.
- Remove the second protective layer and install the heatsink.



Disclaimer Properties of the products may be revised due to changes in the manufacturing process. The property values in this document are not guaranteed. This product is made of silicone, this means silicone oil may exude from the product and low molecular siloxane may vaporize depending on operating conditions. This product is designed and manufactured for general industrial use only. Never use this product for medical, surgical purposes and/or other purposes. Never use this product for the purpose of implantation and/or other purposes by which a part of the product remains in the human body. Before using safety must be evaluated and verified by the purchaser. Contents described in the document do not guarantee performances and qualities required for the purchaser's specific purposes. Statements concerning possible or suggested uses made herein may not be relied upon.
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